

# APPROVAL SHEET

# WW12R, WW08R, WW06R

±1%, ±5%

Metal low ohm power chip resistors Size 1206 (1W), 0805 (0.5W), 0603 (0.33W) Sensing Type

\*Contents in this sheet are subject to change without prior notice.



#### **FEATURE**

- 1. Metal ultra low and stable TCR performance
- 2. High power rating and compact size
- 3. High reliability and stability
- 4. Reduced size of final equipment
- 5. RoHS compliant & Halogen free & Lead free

# **APPLICATION**

- Power supply
- PDA
- Digital meter
- Computer
- Automotives
- · Battery charger
- DC-DC power converter

#### **DESCRIPTION**

The resistors are constructed in a high grade low resistive metal body. The resistive layer is covered with a protective coat and printed a resistance marking code over it. Finally, the two external end terminations are added. For ease of soldering the outer layer of these end terminations is a Lead free terminations.



Fig 1. Construction of Chip-R



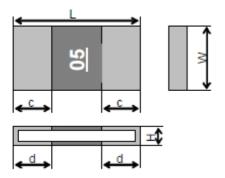
# **QUICK REFERENCE DATA**

Item		General Specification		
Series No.	WW06R	WW08R	WW12R	
Size code	Size code 0603 ( 1608 )		1206 (3216)	
Resistance Tolerance	±5% , ±1%			
Resistance Range	5, 10, 15mΩ	4, 5, 10mΩ,	1 ~ 15 mΩ	
TCR (ppm/°C)	±70 ppm/°C			
Max. power at T <sub>amb</sub> =70°C	1/3 W	1/2 W	1W	
Max. Operation Current (DC or RMS)	8.1A, 5.7A, 4.7A	7A, 10A, 11.1A	31.6A ~ 8.2A	
Operation temperature	-55 ~ +155°C			

Note: Max. Operation Current: So called RCWC (Rated Continuous Working Current) is determined by

 $RCWC = \sqrt{Rated Power / Resistance Value}$  listed above.

# **MECHANICAL DATA**



Unit: mm

Туре	Size (inch)	Resistance	L (mm)	W (mm)	H (mm)	c (mm)	d (mm)
		5mΩ			0.33±0.10	0.20±0.10	0.50±0.10
WW06R	0603	10mΩ	1.60±0.10	0.80±0.10	0.30±0.10	0.20±0.10	0.30±0.10
		15mΩ		0.22±0.10	0.20±0.10	0.20±0.10	
		4mΩ			0.30±0.10	0.30±0.10	0.65±0.10
WW08R	0805	5mΩ	2.0±0.15	1.25±0.15	0.30±0.10	0.30±0.10	0.58±0.20
		10mΩ			0.22±0.10	0.30±0.10	0.47±0.20
WW12R	1206	1mΩ	3.2±0.15	1.60±0.15	0.32±0.10	1.10	±0.25
		2mΩ			0.32±0.10	0.50	±0.25
		3mΩ			0.35±0.10	0.70±0.25	1.30±0.25
		4mΩ			0.35±0.10	1.10:	<u>⊧</u> 0.25
		5mΩ			0.35±0.10	1.00	<u></u> ±0.25
		6mΩ			0.35±0.1	0.80	±0.25

7mΩ		0.35±0.1	0.70±0.25
8mΩ		0.35±0.1	0.50±0.25
9mΩ		0.28±0.1	0.55±0.25
10mΩ		0.28±0.1	0.50±0.25
11mΩ		0.22±0.1	0.80±0.25
12mΩ		0.22±0.1	0.70±0.25
13mΩ		0.22±0.1	0.60±0.25
14mΩ		0.22±0.1	0.55±0.25
15mΩ		0.22±0.1	0.50±0.25

#### **MARKING**

WW12R/WW08R each resistor is marked with a 2-digit code with underline on the protective coating to designate the nominal resistance value. WW06R has no marking!

Example:

 $\frac{05}{10} = 0.005\Omega$   $\frac{10}{10} = 0.010\Omega$ 

# **FUNCTIONAL DESCRIPTION**

# **Derating curve**

The power that the resistor can dissipate depends on the operating temperature; see Fig.2

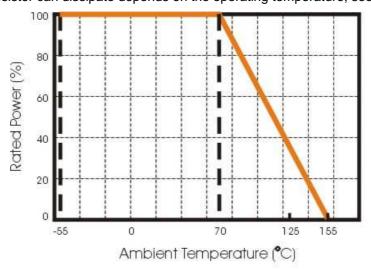


Fig.2 Maximum dissipation in percentage of rated power As a function of the ambient temperature



#### **SOLDERING CONDITIONS**

The robust construction of chip resistors allows them to be completely immersed in a solder bath of 260°C for 10 seconds. Therefore, it is possible to mount Surface Mount Resistors on one side of a PCB and other discrete components on the reverse (mixed PCBs).

Surface Mount Resistors are tested for solderability at 245°C during 3 seconds within lead-free solder bath. The test condition for no leaching is 260°C for 30 seconds. Typical examples of soldering processes that provide reliable joints without any damage are given in Fig

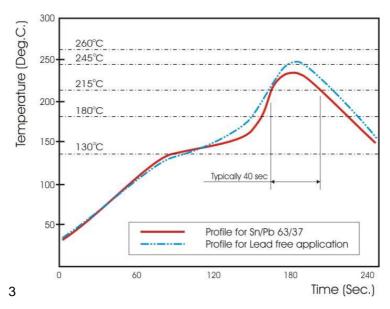


Fig 3. Infrared soldering profile for Chip Resistors WWxxR

#### **CATALOGUE NUMBERS**

The resistors have a catalogue number starting with .

WW06 R		R005 J		Т	L
Size code	Type code	Resistance code	Tolerance	Packaging code	Termination code
WW06 : 0603	R : 1/3W, 0603	R is first digit followed by 3	J : ±5%	T:7" reel	L = Sn base
WW08 : 0805	1/2W, 0805	significant digits.	F : ±1%	Q : 10" reel	(lead free)
WW12 :1206	1W, 1206	$0.010\Omega = R010$			
		$0.005\Omega = R005$			

Reeled tape packaging : 8mm width paper taping 5,000pcs per 7" reel. 10,000pcs per 10" reel.



# **TEST & REQUIREMENTS**

Table-4(1)

No.	Test items	Condition of test (JIS C 5201–1)	Performance requirements
1	Visual examination	Sub-clause 4.4.1 Checked by visual examination.	As in 4.4.1 The marking shall be legible, as checked by visual examination.
2	Dimension	Sub-clause 4.4.2	As specified in Table-3 of this specification.
	Resistance	Resistance value shall be measured by mounting the substrate of the following condition. $\begin{array}{c} \text{Current teminal} \\ \text{Copper clad} \\ \text{Copper clad} \\ \text{Copper clad} \\ \text{Solder resist} \\ \text{Copper clad} \\ \text{Solder resist} \\ \text{Copper clad} \\ Copper$	As in 4.5.2  The resistance value shall correspond with the rated resistance taking into account the specified tolerance.
3	Voltage proof	Sub-clause 4.7 Method: 4.6.1.4(See Figure–5) Test voltage: Alternating voltage with a peak value of 1.42 times the insulation voltage. Duration: 60 s±5 s Insulation resistance Test voltage: Insulation voltage	No breakdown or flash over $R \geq 1 \; G\Omega$
4	Solderability	Duration: 1 min.  Sub-clause 4.17  Without aging Flux: The resistors shall be immersed in a non-activated soldering flux for 2 s.  Bath temperature: 235 °C±5 °C Immersion time: 2 s±0.5 s	As in 4.17.4.5 The terminations shall be covered with a smooth and bright solder coating.
5	Overload (in the mounted state)  Solvent resistance of the marking	Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure–3 Sub-clause 4.13 The applied voltage shall be 2.5 times the rated voltage or the current corresponding to. Duration: 2 s Visual examination Resistance Sub-clause 4.30 Solvent: 2-propanol Solvent temperature: 23 °C±5 °C Method 1 Rubbing material: cotton wool	No visible damage ΔR≤±1% Legible marking

Table-4(2)

	Table-4(Z)					
No	Test items	Condition of test (JIS C 5201–1)	Performance requirements			
6	Mounting	Sub-clause 4.31				
		Substrate material: Epoxide woven glass				
		Test substrate: Figure–4				
	Bound strength of the end	Sub-clause 4.33				
	face plating	Bent value: 1 mm				
		Resistance	ΔR≤±1%			
	Final measurements	Sub-clause 4.33.6				
		Visual examination	No visible damage			
7	Resistance to soldering heat	Sub-clause 4.18				
		Solder temperature: 260 °C±5 °C				
		Immersion time: 10 s±0.5 s				
		Visual examination	As in 4.18.3.4			
			No sign of damage such as cracks.			
	_	Resistance	ΔR≤±1%			
	Component solvent	Sub-clause 4.29				
	resistance	Solvent: 2-propanol				
		Solvent temperature: 23 °C±5 °C				
		Method 2				
		Recovery: 48 h				
		Visual examination	No visible damage			
		Resistance	ΔR≤±1%			
8	Mounting	Sub-clause 4.31				
		Substrate material: Epoxide woven glass				
		Test substrate: Figure–3				
	Adhesion	Sub-clause 4.32				
		Force: 5 N				
		Duration: 10 s±1 s				
		Visual examination	No visible damage			
	Rapid change temperature	Sub-clause 4.19				
		Lower category temperature:-55 °C				
		Upper category temperature:+155 °C				
		Duration of exposure at each temperature: 30				
		min.				
		Number of cycles: 5 cycles.	No visible demons			
		Visual examination	No visible damage			
		Resistance	ΔR≤±1%			



Table-4(3)

No	Test items	Condition of test (JIS C 5201–1)	Performance requirements
9	Climatic sequence	Sub-clause 4.23	·
	-Dry heat	Sub-clause 4.23.2	
	_	Test temperature: +155 °C	
		Duration: 16 h	
	–Damp heat, cycle	Sub-clause 4.23.3	
	(12+12hour cycle)	Test method: 2	
	First cycle	Test temperature: 55 °C	
		[Severity(2)]	
	-Cold	Sub-clause 4.23.4	
		Test temperature –55 °C	
	5	Duration: 2h	
	-Damp heat, cycle	Sub-clause 4.23.6	
	(12+12hour cycle)	Test method: 2	
	Remaining cycle	Test temperature: 55 °C	
		[Severity (2)]	
	–D.C. load	Number of cycles: 5 cycles	
	-D.C. load	Sub-clause 4.23.7 The applied current shall be the rated current.	
		Duration: 1 min	
		Visual examination	
		Resistance	No visible damage
			∆R≤±(1%+0.0005ohm)
10	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
		Test substrate: Figure-3	
	Endurance at 70 °C	0.1.1.4254	
	Lildulance at 70 C	Sub-clause 4.25.1	
		Ambient temperature: 70 °C±2 °C Duration: 1000 h	
		The current shall be applied in cycles of 1.5 h	
	on and 0.5 h.		
		The applied current shall be the rated current	
	Examination at 48 h, 500 h and 1000 h:		
		Visual examination	
		Resistance	No visible damage
			∆R≤(1%+0.0005ohm)



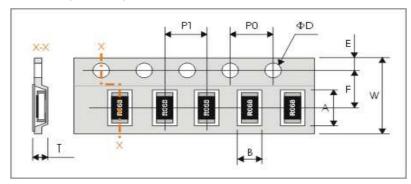
Table-4(4)

	Table—4(4)						
No	Test items	Condition of test (JIS C 5201–1)	Performance requirements				
11	Mounting	Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure–3					
	Variation of resistance with temperature	Sub-clause 4.8 +20 °C / +155 °C	As in Table–1				
12	Mounting	Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure–3					
	Damp heat, steady state	Sub-clause 4.24 Ambient temperature: 40 °C±2 °C Relative humidity: 93 ½ % Without current applied. Visual examination	No visible damage Legible marking				
		Resistance	ΔR≤±(1%+0.0005ohm)				
13	Dimensions (detail)	Sub-clause 4.4.3	As in Table–4				
	Mounting	Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure–3					
	Endurance at upper category temperature	Sub-clause 4.25.3 Ambient temperature:155 °C±2 °C Duration: 1000 h Examination at 48 h, 500 h and 1000 h: Visual examination Resistance	No visible damage ∆ R ≤ ±(1%+0.0005ohm)				



# **PACKAGING**

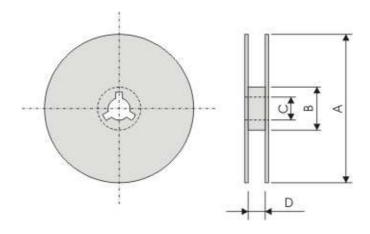
# Paper Tape specifications (unit :mm)



Symbol	Α	В	W	F	E
WW06R	1.90±0.20	1.15±0.15			
WW08R	2.50±0.20	1.65±0.15	8.00±0.20	3.50±0.05	1.75±0.10
WW12R	3.60±0.20	2.00±0.15			

Symbol	P1	P0	ΦD	Т
WW06R				0.8 max.
WW08R	4.00±0.10	4.00±0.10	$\Phi$ 1.50 $^{+0.1}_{-0.0}$	1.0 max.
WW12R				1.0 max.

# **Reel dimensions**



Symbol	Α	В	С	D
7"	Ф180.0 -1.5	Φ60.0±1.0	13.0±0.2	9.0 +1.0
10"	Φ254.0 ±2.0	Φ100.0±1.0	13.0±0.2	9.0 +1.0

# **Taping quantity**

- Chip resistors 5,000 pcs per 7" reel; 10,000pcs per 10" reel.